

IN THE CLAIMS:

The following is a complete listing of claims in this application.

1. (currently amended) A light emitting ~~element~~ diode comprising:

a base made of heat conductive material and having a heat radiation surface ~~formed on a surface thereof~~;

at least one wire plate made of an insulation material and secured to an upper surface of the base;

exposing means for forming an exposed mounting area on the surface of the base;

conductive patterns formed on the wire plate;

a light emitting ~~chip~~ diode element secured to the base at the mounting area; and

connecting means for electrically connecting the light emitting ~~chip~~ diode element to the conductive patterns.

2. (currently amended) The light emitting ~~element~~ diode according to claim 1 wherein the heat radiation surface is provided on an underside of the base.

3. (currently amended) The light emitting ~~element~~ diode according to claim 1 wherein the exposing means is a perforated hole formed in the wire plate.

4. (currently amended) The light emitting ~~element~~ diode according to claim 1 wherein the connecting means comprises a plurality of lead wires.

5. (withdrawn and currently amended) The light emitting ~~element~~ diode according to claim 1 wherein the connecting means comprises a lead wire connected to the conductive pattern and the exposed mounting area of the base for connecting a terminal on an underside of the light emitting chip to an electric source.

6. (currently amended) The light emitting ~~element~~ diode according to claim 1 further comprising an encapsulating member for protecting the light emitting ~~chip~~ diode element.

7. (withdrawn and currently amended) The light emitting ~~element~~ diode according to claim 1 further comprising cooling fins provided on the heat radiation surface of the base.

8. (withdrawn and currently amended) The light emitting ~~element~~ diode according to claim 1 further comprising heat radiation holes formed in one of sides of the base.

9. (withdrawn and currently amended) The light emitting ~~element~~ diode according to claim 5 further comprising a projection formed on an upper surface of the base, and a terminal portion provided on an upper surface of the projection so as to be electrically connected to the terminal on the underside of the light emitting ~~chip~~ diode element.

10. (currently amended) A light emitting ~~device~~ diode comprising:

a base made of heat conductive material and having a flat plate shape and a heat radiation surface formed on a surface thereof;

at least one wire plate made of an insulation material and secured to an upper surface of the base;

exposing means for forming an exposed mounting area on the surface of the base;

conductive patterns secured to the wire plate;

a light emitting ~~chip~~ diode element secured to the base at the mounting area;

connecting means for electrically connecting the light emitting ~~chip~~ diode element to the conductive patterns;

a print substrate having conductive patterns provided on an underside thereof and secured to the conductive patterns on

the wire plate so as to electrically connect both the conductive patterns.

11. (currently amended) The light emitting ~~device~~ diode according to claim 10 wherein print substrate has a hole for discharging the light emitted from the light emitting ~~chip~~ diode element.

12. (currently amended) The light emitting ~~device~~ diode according to claim 10 further comprising a heat radiating member secured to an underside of the base.

13. (withdrawn and currently amended) A light emitting ~~device~~ diode comprising:

a base made of heat conductive material and having a flat plate shape and a heat radiation surface formed on a surface thereof;

at least one wire plate made of an insulation material and secured to an upper surface of the base;

exposing means for forming an exposed mounting area on the surface of the base;

conductive patterns secured to the wire plate;

a light emitting ~~chip~~ diode element secured to the base at the mounting area;

connecting means for electrically connecting the light emitting ~~chip~~ diode element to the conductive patterns;

heat pipes projected from a side wall of the base; and

a heat radiation member secured to ends of the heat pipes.

14. (withdrawn and currently amended) A light emitting diode device having a plurality of ~~heat~~ light emitting ~~elements~~ diodes, each of the light emitting ~~elements~~ diodes comprising:

a base made of heat conductive material and having a flat plate shape and a heat radiation surface formed on a surface thereof;

at least one wire plate made of an insulation material and secured to an upper surface of the base;

exposing means for forming an exposed mounting area on the surface of the base;

conductive patterns secured to the wire plate;

a light emitting ~~chip~~ diode element secured to the base at the mounting area;

connecting means for electrically connecting the light emitting ~~chip~~ diode element to the conductive patterns;
wherein

the light emitting diode device has a heat radiation member ~~made of a flexible material~~, and the light emitting ~~elements~~ diodes are supported on a surface of the heat radiation member.

Claim 15 (canceled).